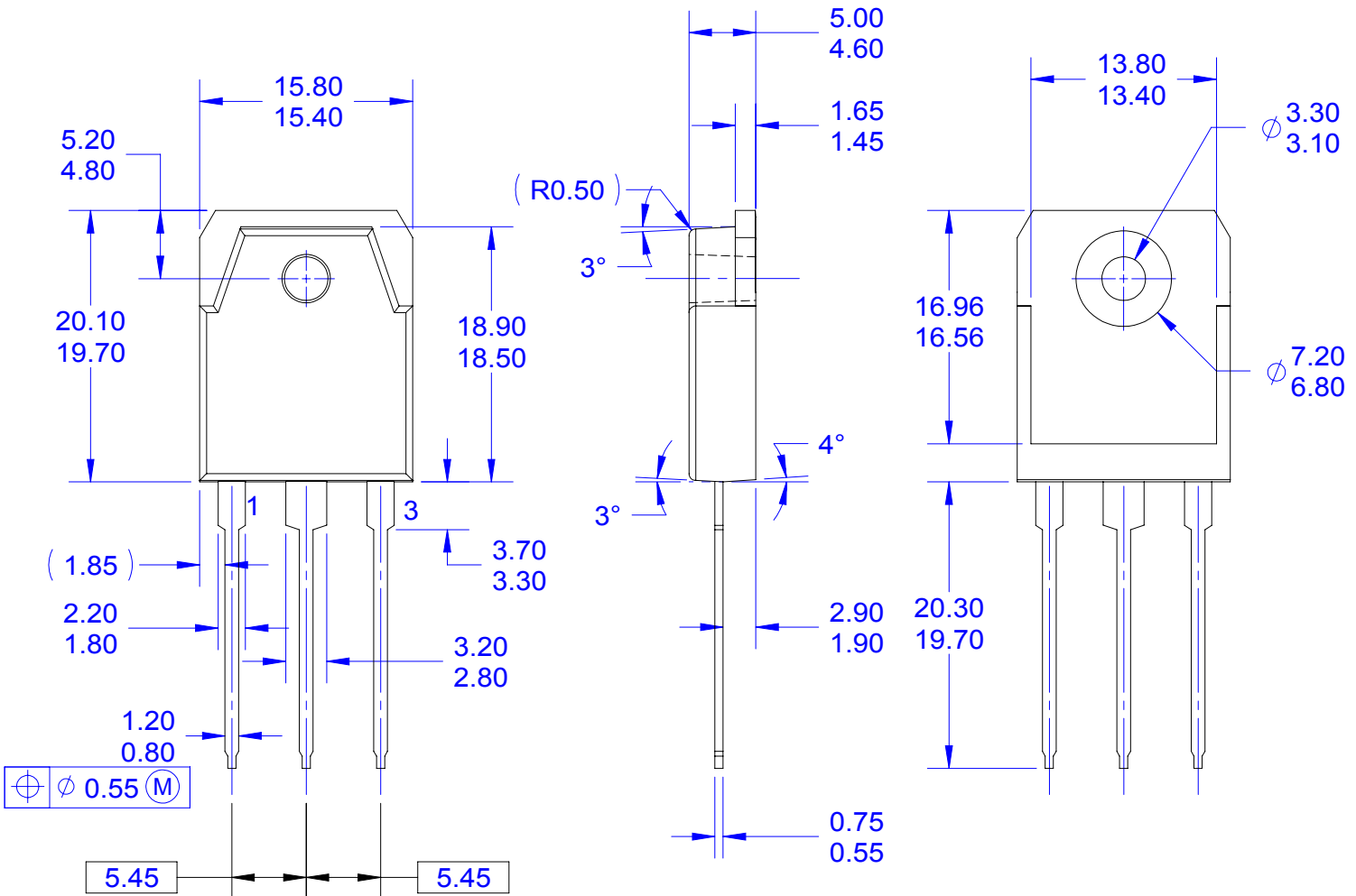


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NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSION AND TOLERANCING PER ASME14.5
- D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- E) THIS PACKAGE IS INTENDED ONLY FOR T03PN.
- F) DRAWING FILE NAME: T03P03AREV4.

APPROVALS		DATE	
DRAWN: BOBOY MALDO		01FEB2010	
CHECKED: KH LEE			
APPROVED: BY HUANG			
APPROVED: HOWARD ALLEN			3LD, T03, PLASTIC, EIAJ SC-65
SCALE: 1:1	FORMERLY: N/A	DRAWING NUMBER: MKT TO3P03A	REV: 4
SHEET: 1 OF 1			